



Material Content Data Sheet



Sales Product Name		BAL 99 E6327		Issued		29. August 2013		
MA#		MA000550600						
Package		PG-SOT23-3-16		Weight*		8.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		229	
	non noble metal	arsenic	7440-38-2	0.000	0.00		2	
	inorganic material	silicon	7440-21-3	0.017	0.20	0.22	1958	2189
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		934	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		311	
	non noble metal	copper	7440-50-8	2.731	30.99	31.12	309893	311200
wire	noble metal	gold	7440-57-5	0.007	0.08	0.08	758	758
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6576	
	plastics	brominated resin	-	0.087	0.99		9863	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.32		13151	
	plastics	epoxy resin	-	1.246	14.14		141377	
	inorganic material	silicondioxide	60676-86-0	4.288	48.64	65.75	486599	657566
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16981	16981
plating	noble metal	silver	7440-22-4	0.100	1.13	1.13	11306	11306
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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